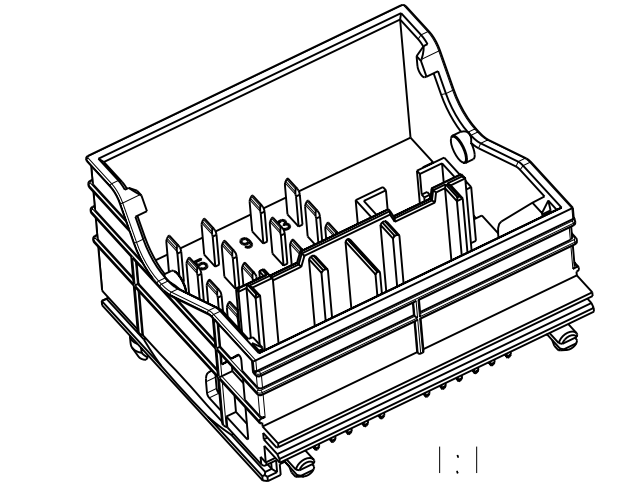
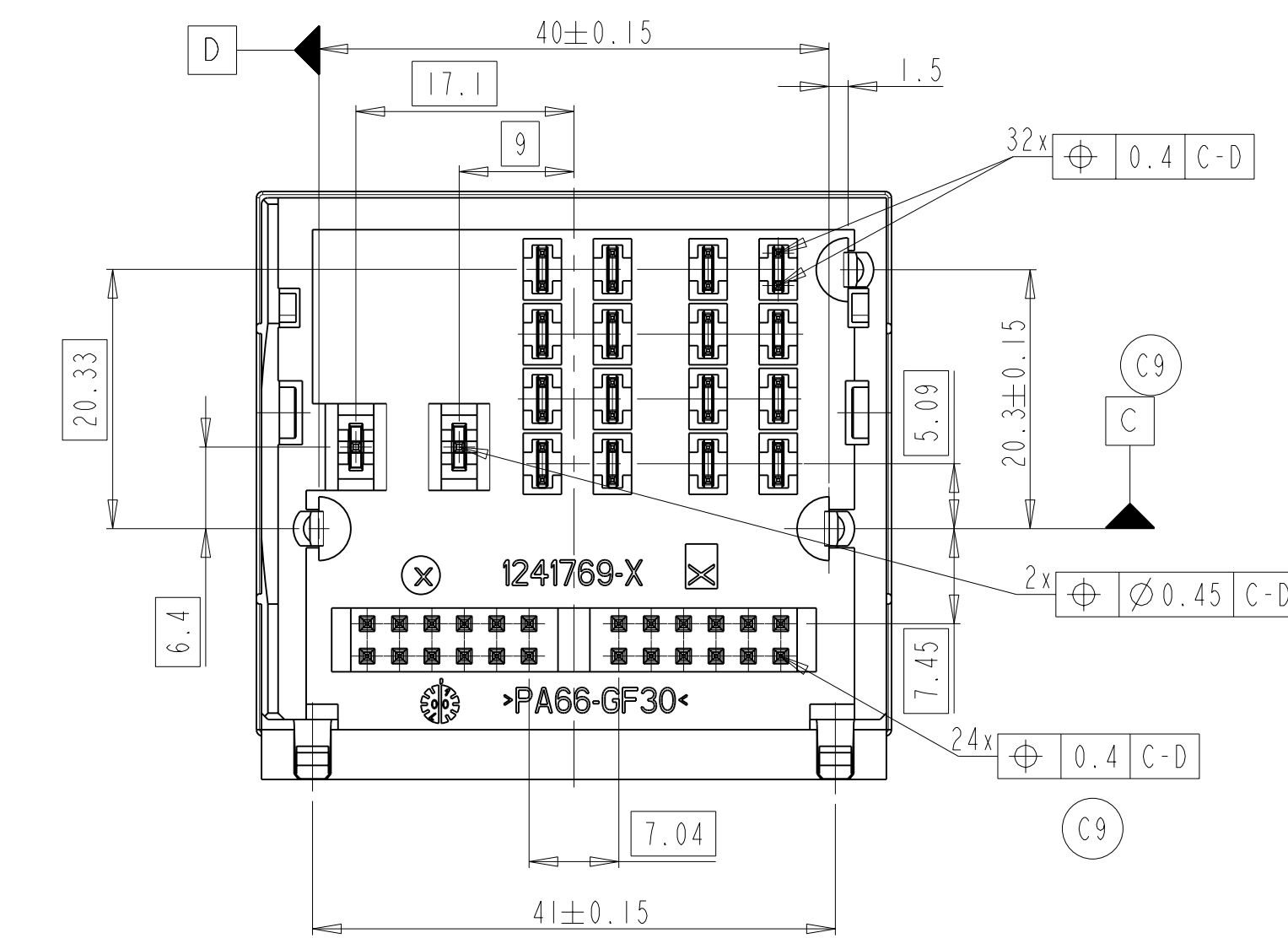
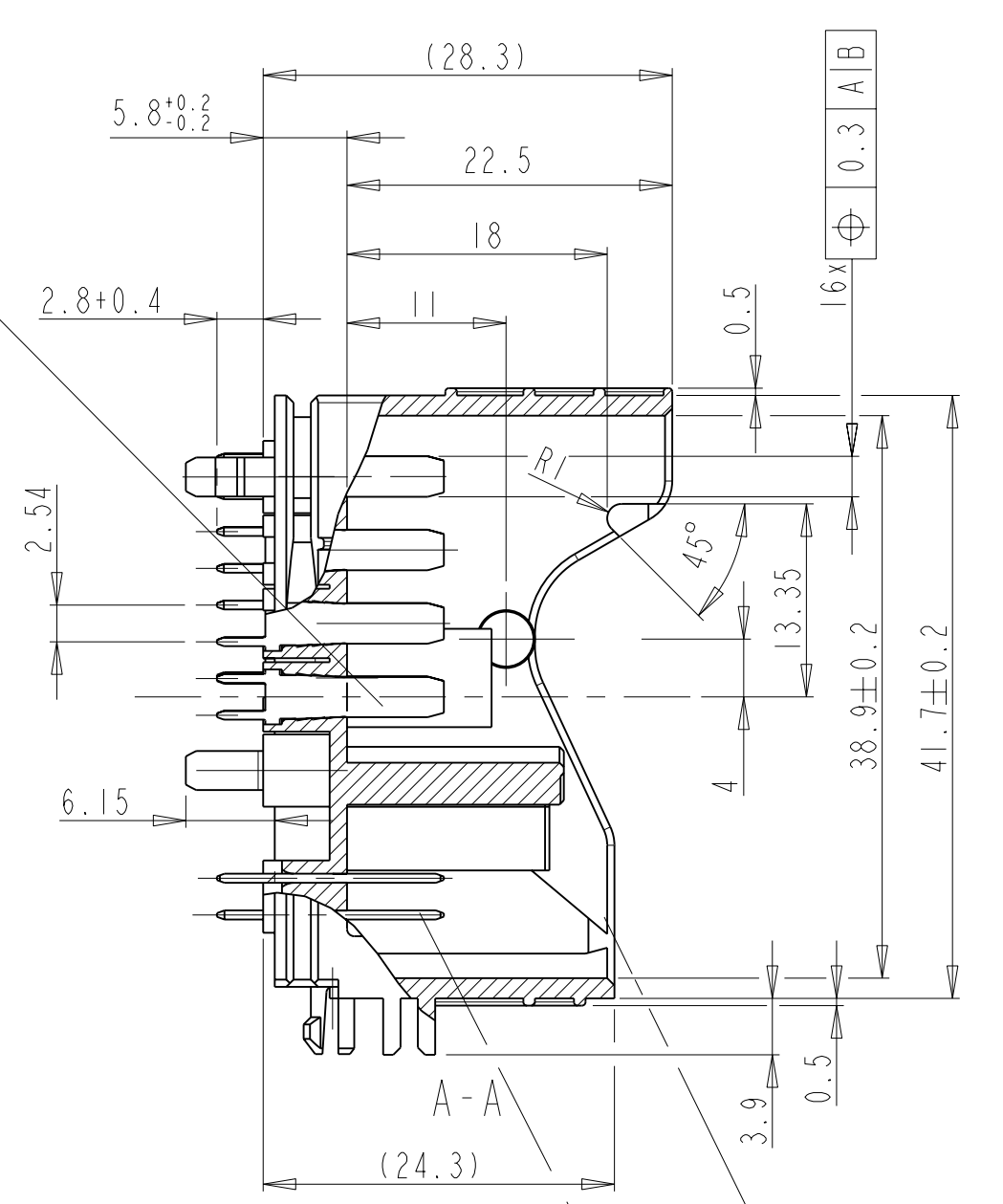
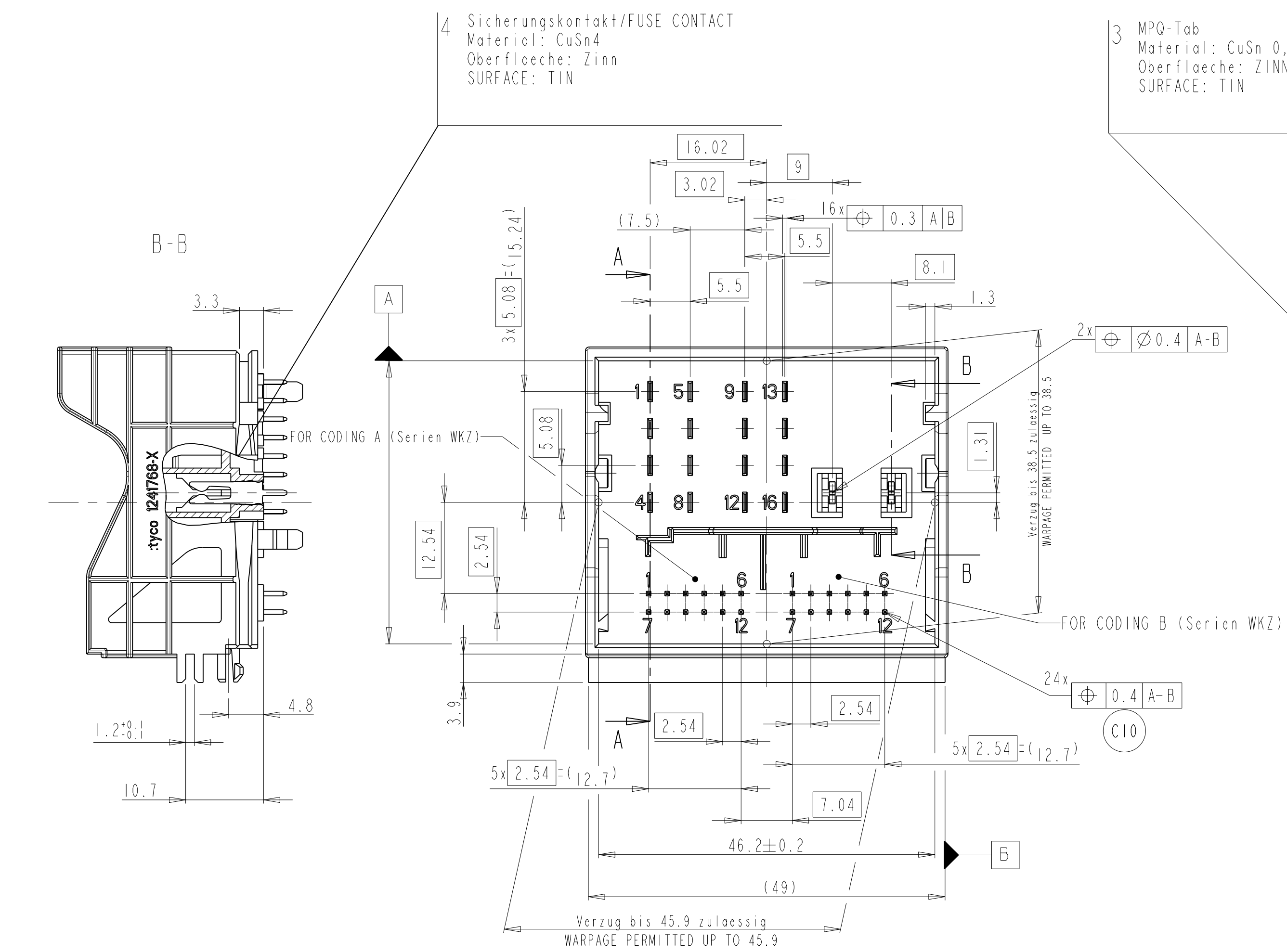
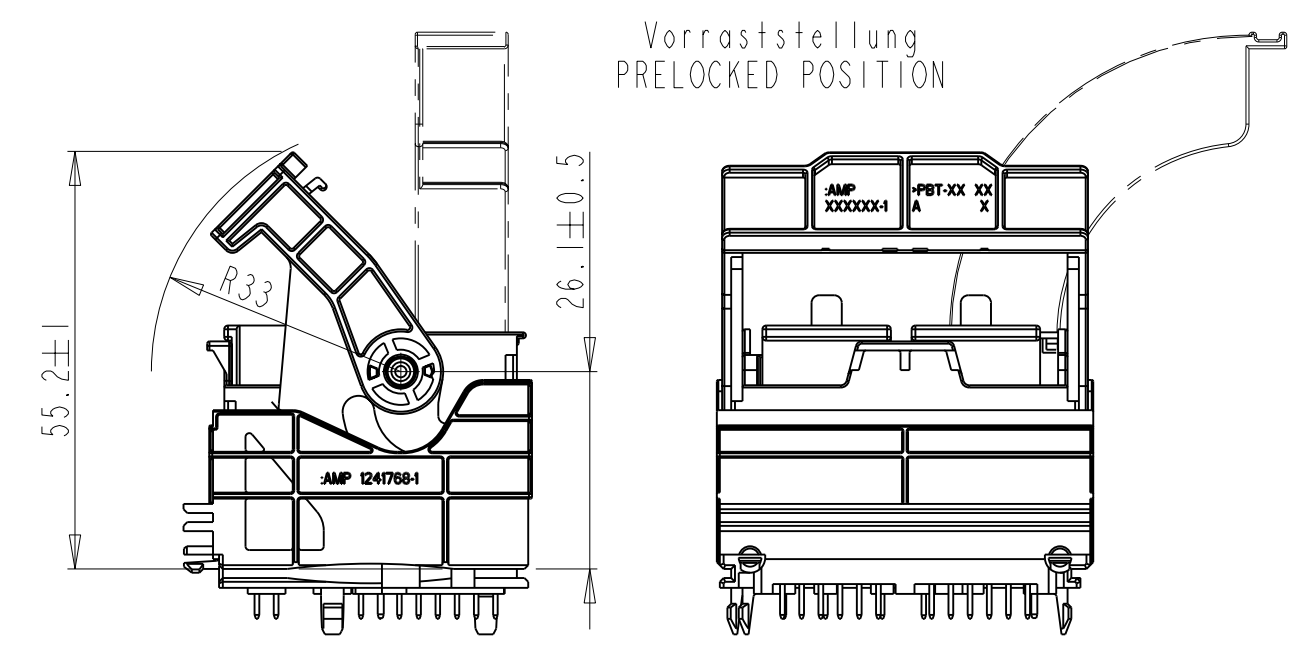
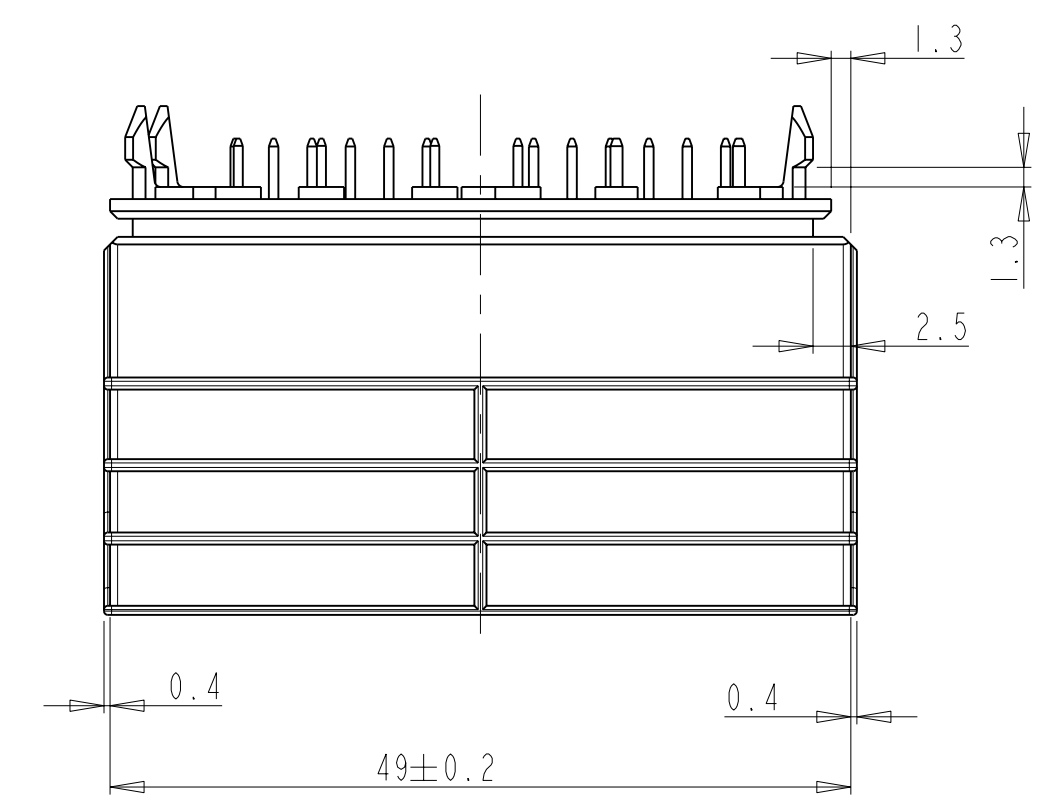
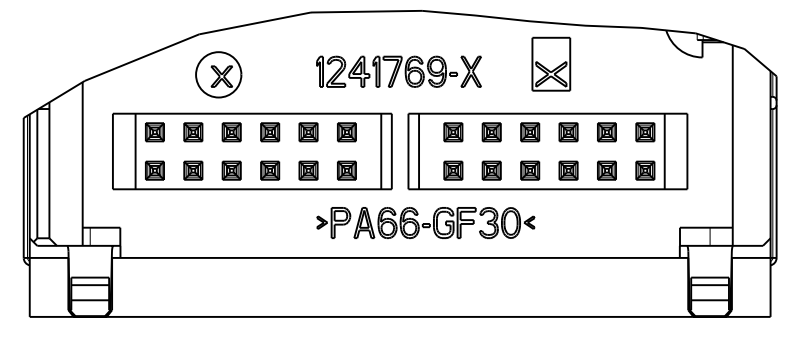


LOC	DIST	P	LTR	REVISIONS	DATE	DWN	APVD
A1	-	C11	-	ECR-08-024870, PN I-1241768-3 hinzu	020CT2008	AL	BF



Materialentnahme
 wahlweise. Gilt fuer
 alle Varianten



Bemerkungen
 NOTES

- 1 Massgebend ist der deutsche Text
 ONLY THE GERMAN-LANGUAGE VERSION SHALL BE BINDING
- 2 Kontaktausdrueckkraft >25N mit Vorschub 25mm/min
 PRESS OUT FORCE OF CONTACTS >25N WITH FORCE 25mm/min
- 3 Verpackung: lagenweise (Karton, Teil), nach Verpackungsanweisung VI241768
 PACKING: IN LAYERS (BOX, SAMPLE), ACC. PACKAGING INSTRUCTION VI241768
- 4 Lotbarkeit gemass DIN IEC 60068-2-20, Alterung 3
 SOLDERABILITY ACCORDING DIN IEC 60068-2-20, AGEING 3
- 5 Einzelheiten der Ausfuehrung bleiben dem Hersteller ueberlassen
 DETAILS OF DESIGN ARE LEFT TO MANUFACTURER
- 6 Produkt darf nur mit Zustimmung von BMW, in Absprache mit FAKRA und VW, geaendert werden
 PRODUCT SHALL BE CHANGED WITH THE AGREEMENT OF BMW, FAKRA AND VW ONLY
- 7 PN I-1241768-2/ I-1241768-3 verpackt in ESD-Tray (PS-leitfaehig) und Karton, nach Verpackungsanweisung VI241768
 PN I-1241768-2/ I-1241768-3 PACKED INTO ESD-TRAY (PS CONDUCTIVE) AND CARTON, ACC. PACKAGING INSTRUCTION VI241768

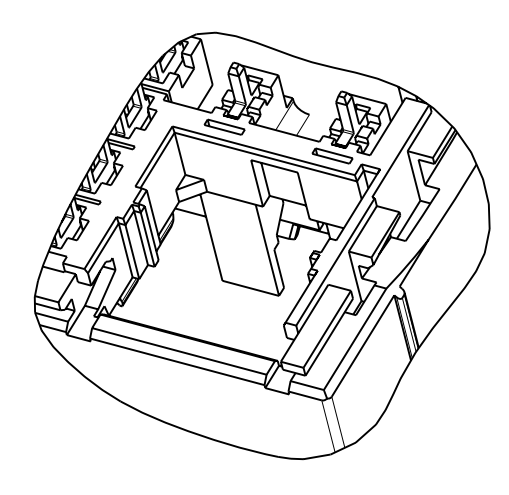
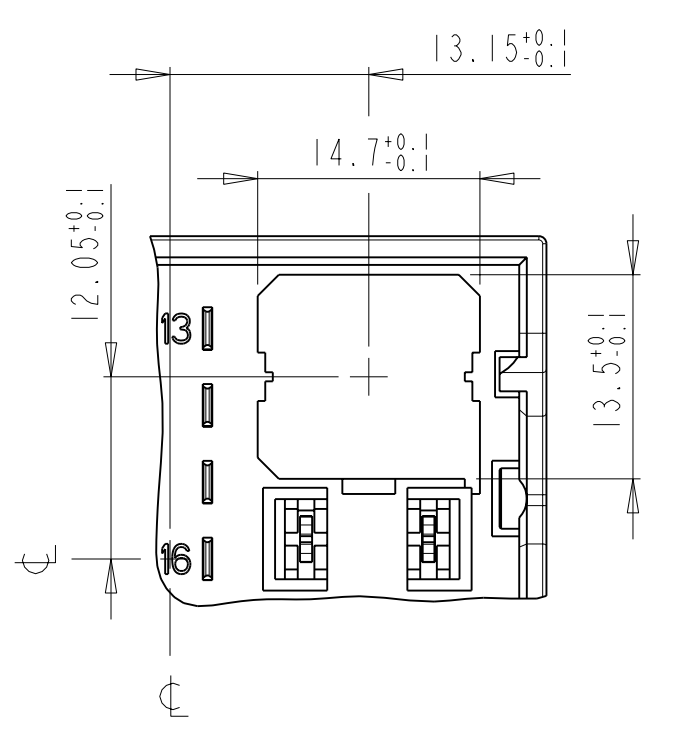
SEE SHEET 2 OF 2	LOC	DIST	P	LTR	REV.	POS.	Stk. QTY.	Benennung DESCRIPTION	Oberflaeche SURFACE	Passend zu: SUITABLE FOR:
SEE SHEET 2 OF 2	I-1241768-3	C	7	-	4	2	ESD- TRAY	BLACK	1241765-2 I-1355035-1	
				3	16	TAB 2.8x0.6	TIN			
				2	24	MOS PIN	TIN			
				5	1	PIN HEADER	LIGHT BLUE			
				-	4	2	FUSE CONTACT	TIN		
SEE SHEET 2 OF 2	I-1241768-2	C	7	-	4	2	ESD-TRAY	BLACK	1241765-2 I-1355035-1	
				3	16	TAB 2.8x0.6	TIN			
				2	24	MOS PIN	TIN			
				5	1	PIN HEADER	BLACK			
				-	4	2	FUSE CONTACT	TIN		
SEE SHEET 2 OF 2	1241768-7	B	3	3	16	TAB 2.8x0.6	TIN	1241765-2 I-1355035-1		
				2	4	MOS PIN	TIN			
				10	1	PIN HEADER	BLACK			
				9	1	MINI FUSE, 10A	-			
SEE SHEET 2 OF 2	1241768-5	A	3	4	2	FUSE CONTACT	TIN	1241765-2 I-1355035-1		
				3	16	TAB 2.8x0.6	TIN			
				2	24	MOS PIN	TIN			
				8	1	PIN HEADER	BLACK			
SEE SHEET 2 OF 2	1241768-4	C	3	4	2	FUSE CONTACT	TIN	1241765-2 I-1355035-1		
				3	16	TAB 2.8x0.6	TIN			
				2	-	MOS PIN	-			
SEE SHEET 2 OF 2	1241768-3	C	3	7	1	PIN HEADER	BLACK	1241765-2 I-1355035-1		
				4	2	FUSE CONTACT	TIN			
				3	16	TAB 2.8x0.6	TIN			
SEE SHEET 2 OF 2	1241768-2	C	3	2	-	MOS PIN	-	1241765-2 I-1355035-1		
				6	1	PIN HEADER	BLACK			
				4	2	FUSE CONTACT	TIN			
SEE SHEET 2 OF 2	1241768-1	C	3	4	2	FUSE CONTACT	TIN	1241765-2 I-1355035-1		
				3	16	TAB 2.8x0.6	TIN			
				2	24	MOS PIN	TIN			
SEE SHEET 2 OF 2	TE	REV.	POS.	Stk. QTY.	Benennung DESCRIPTION	Oberflaeche SURFACE	Passend zu: SUITABLE FOR:	Farbe COLOUR	Buchsengehaeuse SOCKET HOUSING	

DWN	M. Maier	29APR99	NAME	Micro Power Quadlok - Micro Quadlok System, PIN HEADER 16+24 POSN. Stiftwanne 16+24-pol.
CHK	J. Hahn	30APR99	PRODUCT SPEC	PRODUKTSPEZ.
APVD			APPLICATION SPEC	VERARBEITUNGSSPEZ.
SCALE	1:1		SIZE	A1 00779
WEIGHT	21g		DRAWING NO.	1241768
CUSTOMER DRAWING	/KUNDENZEICHNUNG	SCALE	5:1	SHEET
				1
				OF
				2

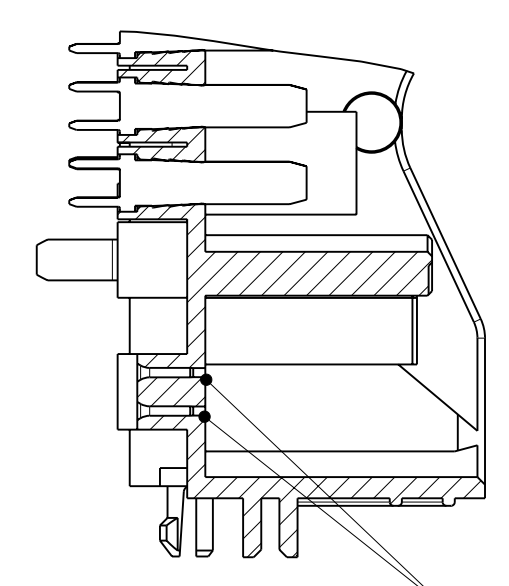
THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION 07. JUL 1988
 WÄHRUNG: METRISCHE ZEICHNUNG FÜR VERFÄHRUNG
 BY TYCO ELECTRONICS CORPORATION. ALL RIGHTS RESERVED. ALLE RECHTE VORBEHALTEN.
 MATR. NR. / PART NO. / PART NO.

LOC	DIST	REV.	DATE	DWN	APVD
A1	-	P	LTH		
PROJECT NO.: 98-52009			SEE SHEET 1		
REVISIONS ÄNDERUNGEN DESCRIPTION BESCHREIBUNG					

POS. 5
 PART NO. 1241768-2
 PART NO. 1-1241768-2
 PART NO. 1-1241768-3

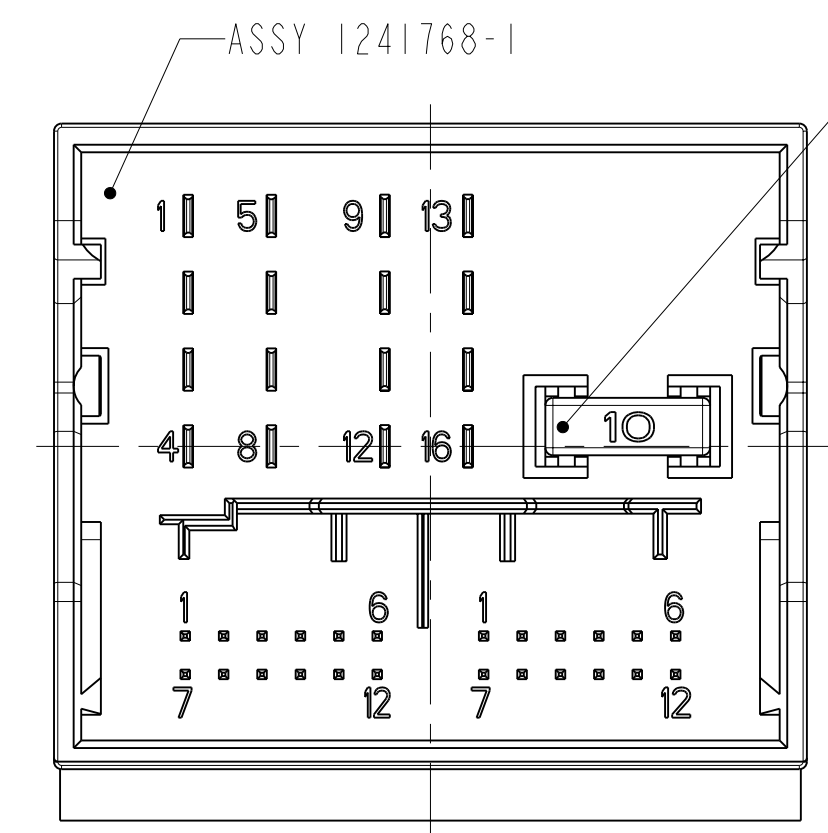


POS. 6
 PART NO. 1241768-3
 restliche Ausfuehrung wie POS.1
 POS.7
 PART NO. 1241768-4
 restliche Ausfuehrung wie POS.5

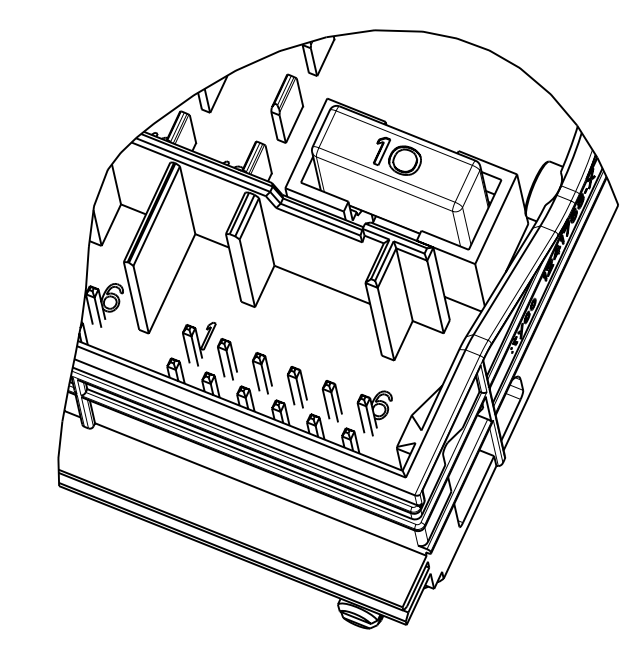


ohne MOS PIN
 WITHOUT MOS PIN

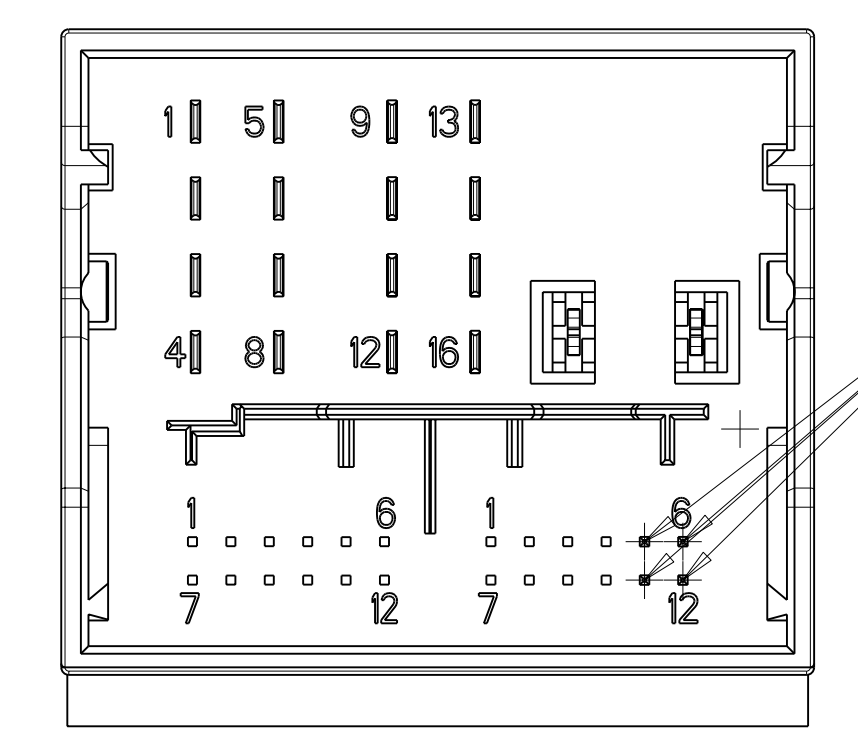
POS. 8
 PART NO. 1241768-5
 restliche Ausfuehrung wie POS.1



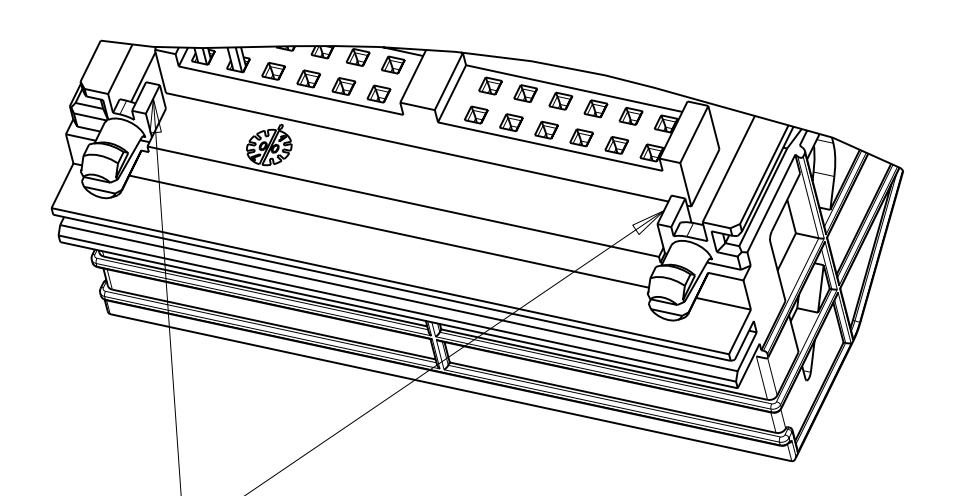
POS.9
 MINI-FUSE



POS. 10
 PART NO. 1241768-7
 restliche Ausfuehrung wie POS.1

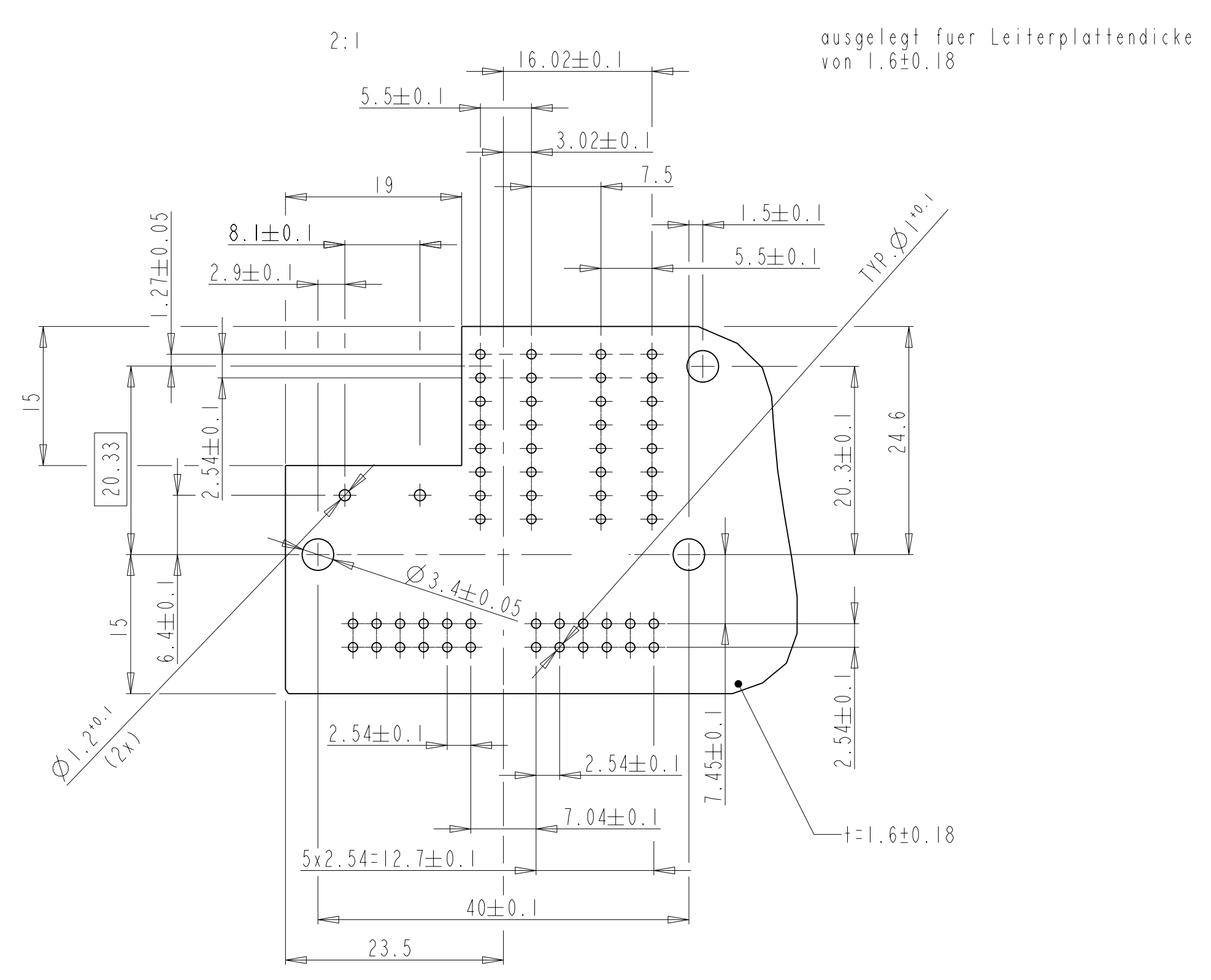


4x MOS PIN

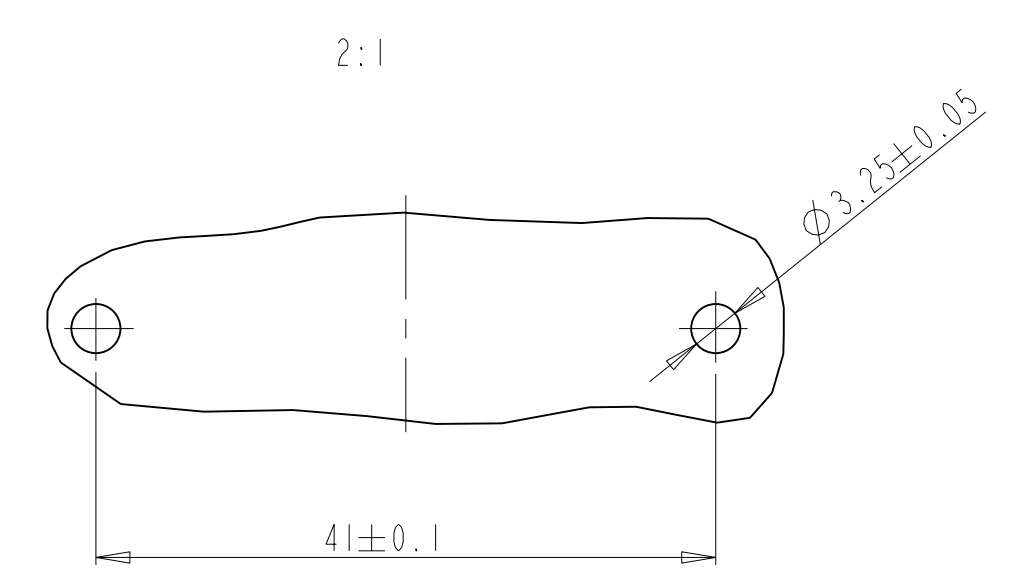


neue Rippen zum Niederhalten
 von Stiflleisten auf der Leiterplatte

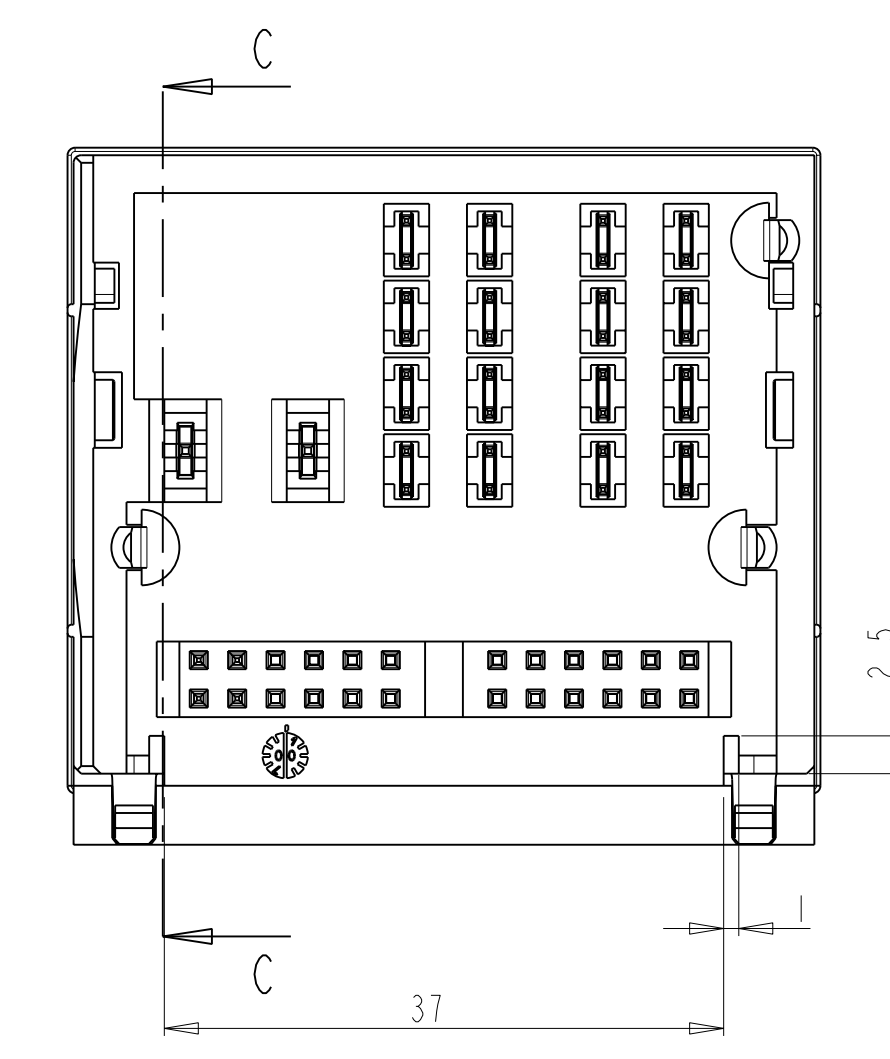
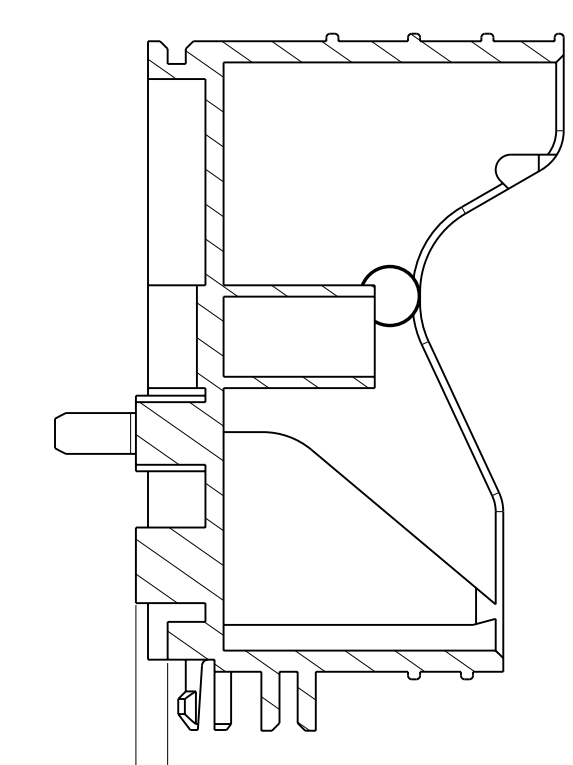
Empfohlenes Lochbild fuer Leiterplatte (Loetseite)
 LAYOUT FOR PCB (SOLDER SIDE)



Empfohlenes Lochbild fuer Boardlocks
 RECOMMENDED LAYOUT FOR BOARDLOCKS



C-C



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CHEK R. Forrell	15MAY2003	NAME Micro Power Quadlok - Micro Quadlok System, PIN HEADER 16+24 POSN. Stiflwane 16+24-pol.	PRODUCT SPEC. PRODUCTSPEZ.	APPLICATION SPEC. VERARBEITUNGSSPEZ.	RESTRICTED TO NUR FÜR
MATERIAL -	FINISH/OBERFLÄCHE/FABRIK -	WEIGHT 21g	SCALE 5:1	SHEET 2	OF 2
CUSTOMER DRAWING		KUNDENZEICHNUNG	SCALE	SHEET	OF